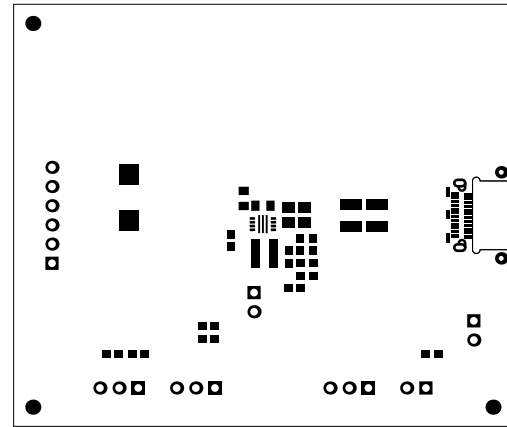
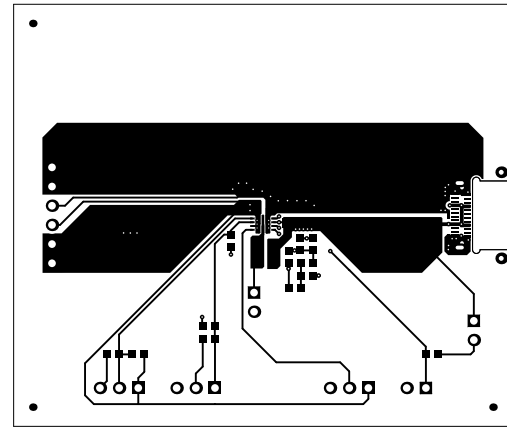


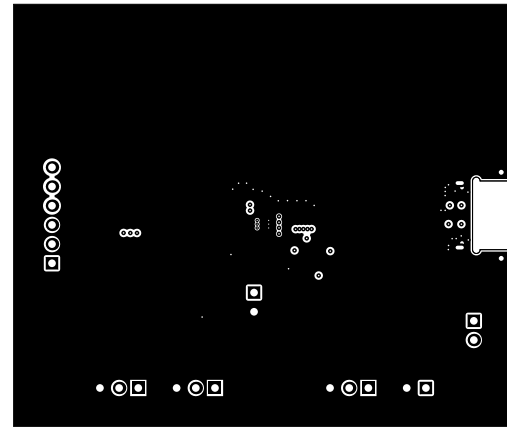
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01567	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01567		
PLOT NAME = Top Overlay	GENERATED : 10/20/2017 12:26:22 PM	TEXAS INSTRUMENTS	



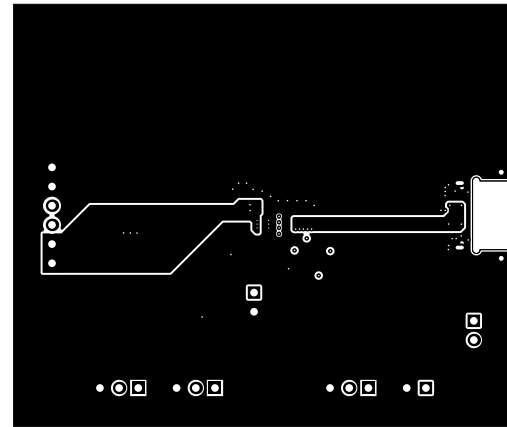
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01567	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01567		
PLOT NAME = Top Solder Mask	GENERATED : 10/20/2017 12:26:23 PM	TEXAS INSTRUMENTS	



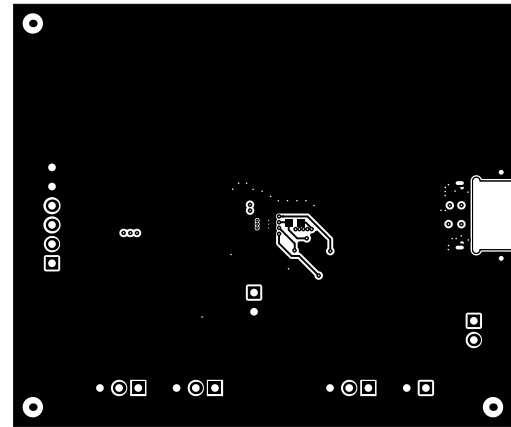
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01567	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01567		
PLOT NAME = Top Layer	GENERATED : 10/20/2017 12:26:24 PM	TEXAS INSTRUMENTS	



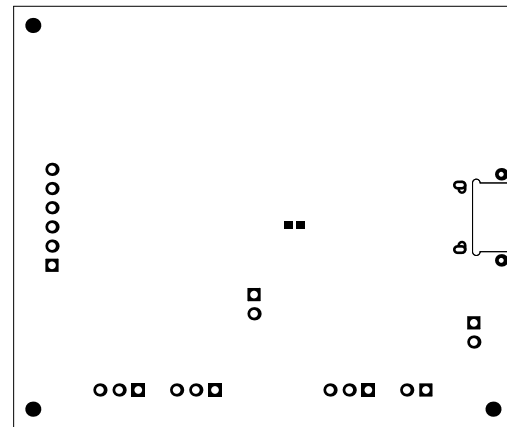
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01567	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01567		
PLOT NAME = Signal Layer 1	GENERATED : 10/20/2017 12:26:25 PM	TEXAS INSTRUMENTS	



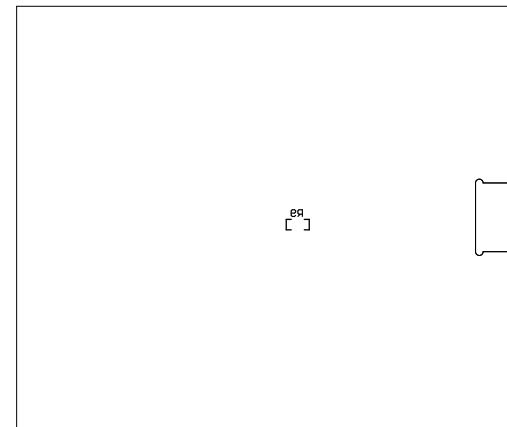
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01567	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01567		
PLOT NAME = Signal Layer 2	GENERATED : 10/20/2017 12:26:26 PM	TEXAS INSTRUMENTS	



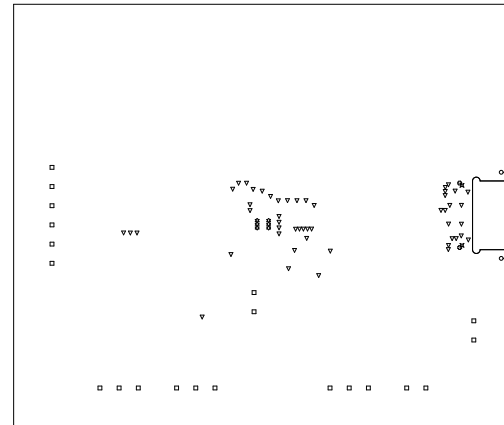
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01567	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01567		
PLOT NAME = Bottom Layer	GENERATED : 10/20/2017 12:26:27 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01567	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01567		
PLOT NAME = Bottom Solder Mask	GENERATED : 10/20/2017 12:26:28 PM	TEXAS INSTRUMENTS	



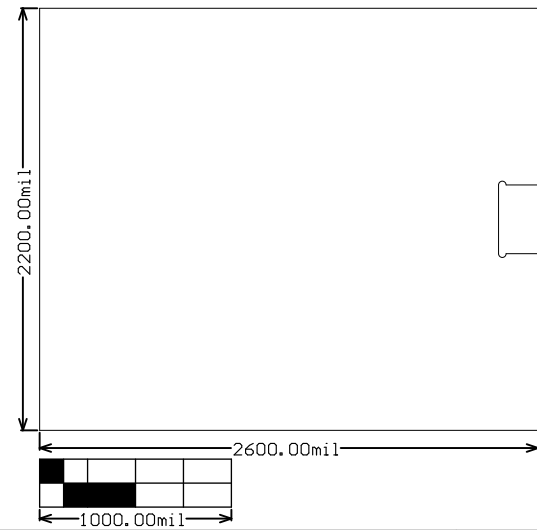
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01567	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01567		
PLOT NAME = Bottom Overlay	GENERATED : 10/20/2017 12:26:29 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
☆	6	6.00mil (0.152mm)	PTH	Round	Top Layer - Bottom Layer	
▽	50	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
○	2	25.59mil (0.650mm)	PTH	Round	Top Layer - Bottom Layer	
□	21	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	19.69mil (0.500mm)	PTH	Slot	Top Layer - Bottom Layer	
⊗	2	19.69mil (0.500mm)	PTH	Slot	Top Layer - Bottom Layer	
83 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01567	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01567		
PLOT NAME = Drill Drawing	GENERATED : 10/20/2017 12:26:30 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01567	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01567		
PLOT NAME = Board Dimensions	GENERATED : 10/20/2017 12:26:31 PM	TEXAS INSTRUMENTS	

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